



Power MOSFETS

DATASHEET

LM20081PLQ8A

P-Channel
Enhancement Mode MOSFET

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Quality Management Systems
ISO 9001:2015 Certificate

P-Channel Enhancement Mode MOSFET

Pin Description

SOP-8L (TOP view)	Symbol	Symbol	P-Channel	Unit
		V_{DSS}	-20	V
		$R_{DS(ON)-Max}$	7.2	$\text{m}\Omega$
		ID	-13	A

Feature

- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Portable Equipment
- Load switch

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM20081PLQ8A	SOP-8L	Tape & Reel	3000 / Tape & Reel	20081 <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit
V_{DSS}	Drain-Source Voltage	-20	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{\text{(1)}}$	Pulse Drain Current Tested	$T_A=25^\circ\text{C}$	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	$\text{-} 13$
		$T_A=70^\circ\text{C}$	-10
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.6
		$T_A=70^\circ\text{C}$	1
$I_{AS}^{\text{(2)}}$	Avalanche Current, Single pulse	$L=0.1\text{mH}$	A
$E_{AS}^{\text{(2)}}$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{\text{(3)}}$	Thermal Resistance-Junction to Ambient	Steady State	78°C/W

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
$\mathbf{BV_{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=-250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-16\text{V}, V_{GS}=0\text{V}$	-	-	-1	μA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu\text{A}$	-0.4	-0.7	-1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
$R_{DS(\text{ON})}^{\text{(4)}}$	Drain-Source On-state Resistance	$V_{GS}=-4.5\text{V}, I_{DS}=-10\text{A}$	-	6	7.2	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_{DS}=-8\text{A}$	-	7.8	10.5	
		$V_{GS}=-1.8\text{V}, I_{DS}=-6\text{A}$	-	10	14	
g_{fs}	Forward Transconductance	$V_{DS}=-5\text{V}, I_{DS}=-5\text{A}$	-	33	-	S
Dynamic Characteristics ⁽⁵⁾						
R_G	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V},$ $\text{Freq.}=1\text{MHz}$	-	8.6	-	Ω
C_{iss}	Input Capacitance	$V_{GS}=0\text{V},$ $V_{DS}=-10\text{V},$ $\text{Freq.}=1\text{MHz}$	-	4136	-	pF
C_{oss}	Output Capacitance		-	618	-	
C_{rss}	Reverse Transfer Capacitance		-	390	-	
$t_{d(\text{ON})}$	Turn-on Delay Time	$V_{GS}=-4.5\text{V}, V_{DS}=-15\text{V},$ $I_D=-1\text{A}, R_{\text{GEN}}=6\Omega$	-	11.9	-	nS
t_r	Turn-on Rise Time		-	22.1	-	
$t_{d(\text{OFF})}$	Turn-off Delay Time		-	142.1	-	
t_f	Turn-off Fall Time		-	274.6	-	
Q_g	Total Gate Charge	$V_{GS}=-2.5\text{V}, V_{DS}=-10\text{V}$ $I_D=-10\text{A}$	-	28.7	-	nC
Q_g	Total Gate Charge	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V},$ $I_D=-10\text{A}$	-	48.2	-	
Q_{gs}	Gate-Source Charge		-	8.05	-	
Q_{gd}	Gate-Drain Charge		-	10	-	
Source-Drain Characteristics						
$V_{SD}^{\text{(4)}}$	Diode Forward Voltage	$I_{SD}=-5\text{A}, V_{GS}=0\text{V}$	-	-0.65	-1.1	V
t_{rr}	Reverse Recovery Time	$I_F=-5\text{A}, V_R=-10\text{V}$	-	41.5	-	nS
Q_{rr}	Reverse Recovery Charge	$dI_F/dt=100\text{A}/\mu\text{s}$	-	32	-	nC

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

P-Channel Typical Characteristics

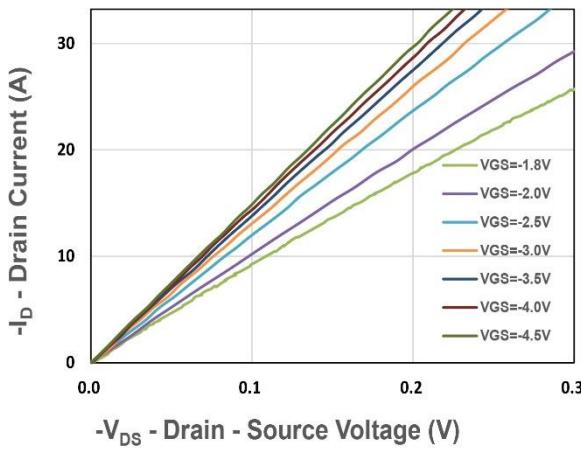


Figure 1. Output Characteristics

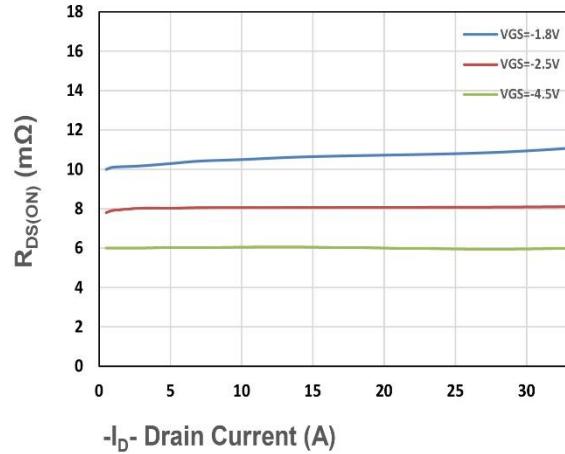


Figure 2. On-Resistance vs. ID

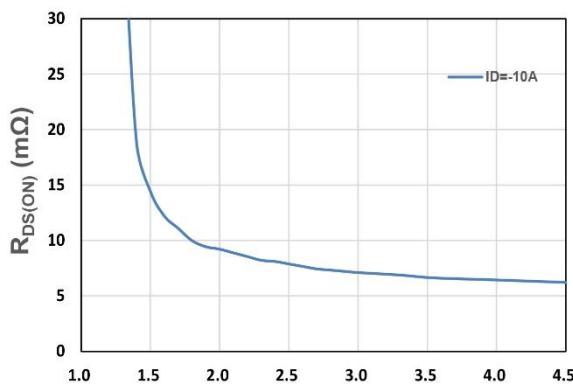


Figure 3. On-Resistance vs. VGS

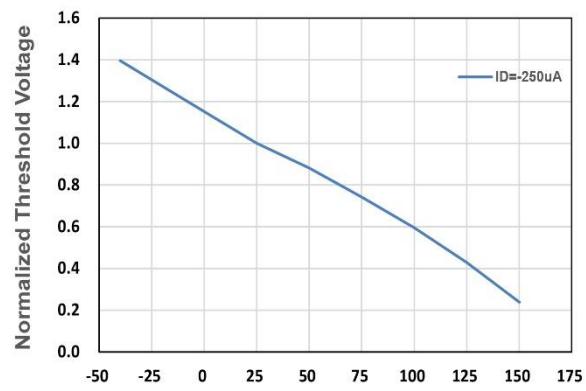


Figure 4. Gate Threshold Voltage

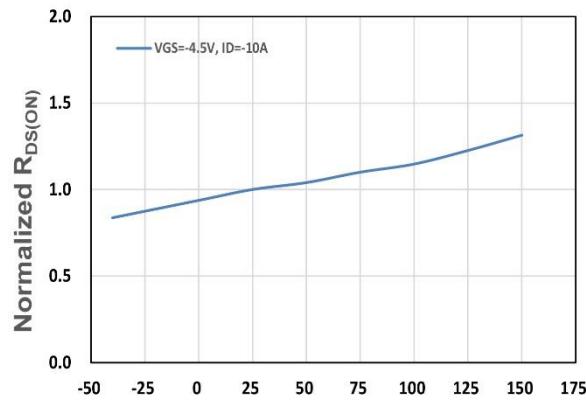


Figure 5. Drain-Source On Resistance

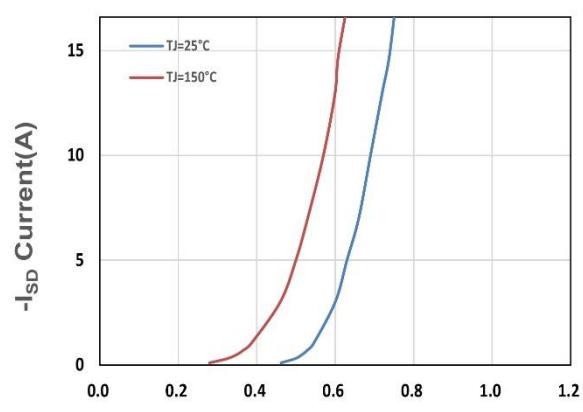
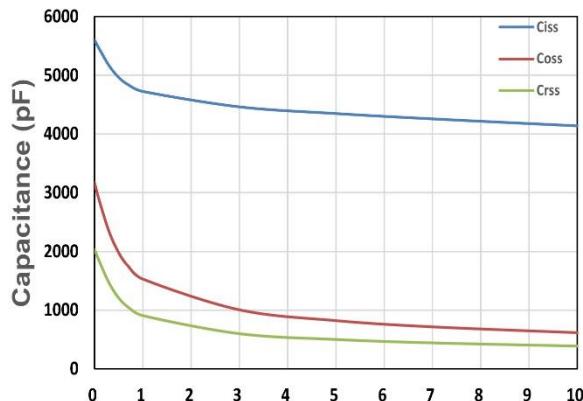
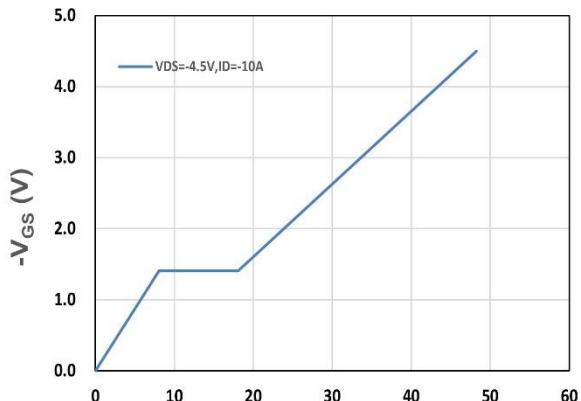


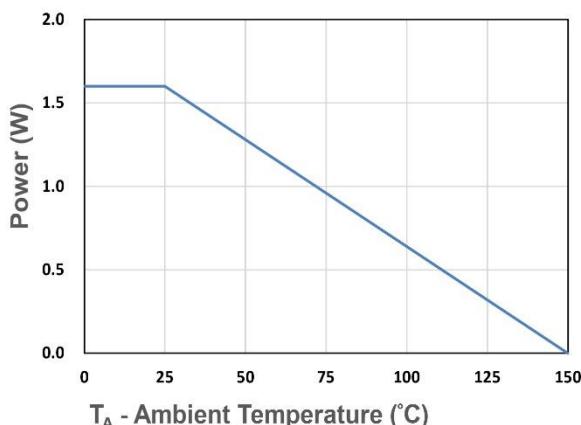
Figure 6. Source-Drain Diode Forward



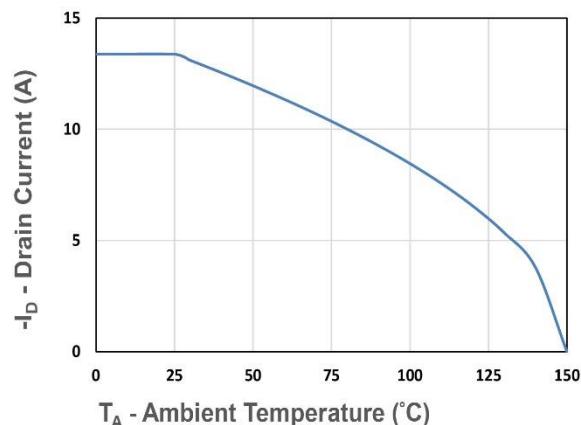
- V_{DS} - Drain - Source Voltage (V)
Figure 7. Capacitance



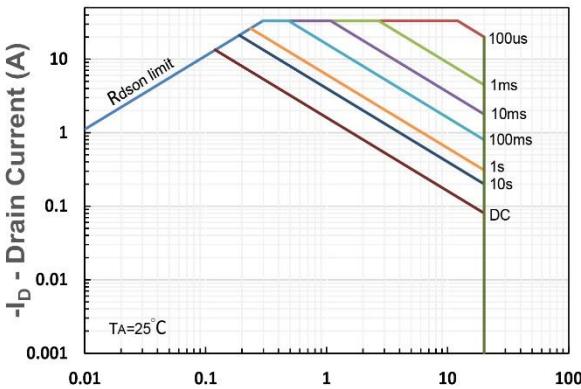
Q_g , Total Gate Charge (nC)
Figure 8. Gate Charge Characteristics



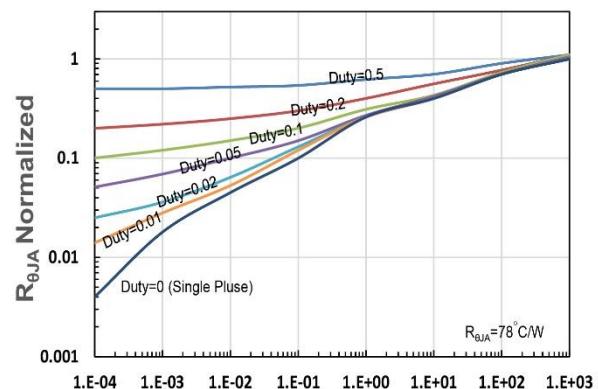
T_A - Ambient Temperature (°C)
Figure 9. Power Dissipation



T_A - Ambient Temperature (°C)
Figure 10. Drain Current



- V_{DS} - Drain-Source Voltage (V)
Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration(s)
Figure 12. $R_{θJA}$ Transient Thermal Impedance